

ABSTRACT

A solvent-free filling material comprising a filler,
a thermosetting resin, a curing agent, and a curing catalyst,
5 wherein the thermosetting resin is an epoxy resin, and the
curing agent is a dicyandiamide curing agent; a multilayer
printed wiring board comprising a substrate, a through-hole,
the filling material filling the through-hole, and a conductor
layer formed on an exposed surface of the filling material
10 in the through-hole; and a process for producing the multilayer
printed wiring board.